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(71) Applicant: FUJIFILM ELECTRONIC MATERIALS
U.S.A., INC. [US/US]; 80 Circuit Drive, N. Kingstown,
Rhode Island 02852 (US).

(72) Inventors: WOJTCZAK, William A.; 6803 Rio Bra-
vo Lane, Austin, Texas 78737 (US). PARK, Keeyoung;
3658 S. Joshua Tree Lane, Gilbert, Arizona 85297 (US).
MIZUTANI, Atsushi; Avenue Marcel Thiry 80 B5, 1200
Woluwe, Saint Lambert (BE).

(74) Agent: ZHANG, Tony et al.; Fish & Richardson P.C., P.O.
Box 1022, Minneapolis, Minnesota 55440-1022 (US).

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(54) Title: SURFACE TREATMENT METHODS AND COMPOSITIONS THEREFOR

(57) Abstract: The disclosure provides methods and compositions therefor for treating a surface wherein a surface treatment layer is formed on the surface, thereby minimizing or preventing pattern collapse as the surface is subjected to typical cleaning steps in the semiconductor manufacturing process.

WO 2018/175682 A1